

**Amendments to the Specification:**

Please amend the CROSS-REFERENCE TO RELATED APPLICATIONS section on page one as follows:

This application is a divisional application of U.S. Patent Application No. 09/649,429, entitled "METHOD FOR FORMING A PLANARIZING PAD FOR PLANARIZATION OF MICROELECTRONIC SUBSTRATES," filed August 28, 2000, now U.S. Patent No. 6,736,869, issued \_\_\_\_\_; May 18, 2004; and is related to U.S. Patent Application No. 10/772,541 [Attorney Docket No. 108298404US2], entitled "APPARATUSES FOR FORMING A PLANARIZING PAD FOR PLANARIZATION OF MICROELECTRONIC SUBSTRATES," filed February 5, 2004, which is a divisional application of U.S. Patent Application No. 09/649,429, both of which are herein incorporated by reference in their entireties.